

iID® module TC78 BML(UHF-LEGIC)

Smart dual band reader accessory for ZEBRA TC78

The iID® module TC78 BML(UHF-LEGIC) is an ultra-compact, low-power RFID accessory combining HF and UHF technologies in a single module. It enables secure badge scanning and long-range part identification delivering fast and reliable communication with multiple RFID transponders and sensor tags. The snap-on design delivers a seamless mechanical fit with instant plug-and-play usability, complemented by simple software integration for fast, effortless deployment across a wide range of platforms. The module provides a robust and flexible solution for RFID applications across logistics, industrial automation, access control and asset management.



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DS-iIDmodule TC78 BML UHF-LEGIC-005.docx

This data sheet is subject to change. Picture may differ from original product.

General:

HF-UHF RFID read/write communication accessory for Zebra Technologies TC78

RFID Interface HF:

Frequencies: iID®3000 based on ISO standards
13.56 MHz
Standards: ISO/IEC 15693, ISO/IEC14443 A/B, ISO/IEC18000-3
Chip support: LEGIC® prime/advant, NXP® Mifare® classic/UL/DESfire, Sony® FeliCa, HID® iClass®
ISO15693 customized, ISO14443 UID only
Operating Distance: approx. 0 ... 5 cm, depending on environmental conditions
Field Direction: from back/rear of the RFID accessory

RFID Interface UHF:

Frequencies: iID®4000 based on ISO standards
865 ... 868 MHz or 902 ... 928 MHz
Standards: RAIN RFID, ISO/IEC 18000-63, GS1 EPC Gen2v2
Chip support: Impinj® Monza/M700/M800, NXP® UCODE®, Allien® Higgs®, TELID®400
Antenna Type: circularly polarized antenna
Operating Distance: 0 ... 150 cm, depending on transponder type and environmental conditions
Field Direction: from back/rear of the RFID accessory

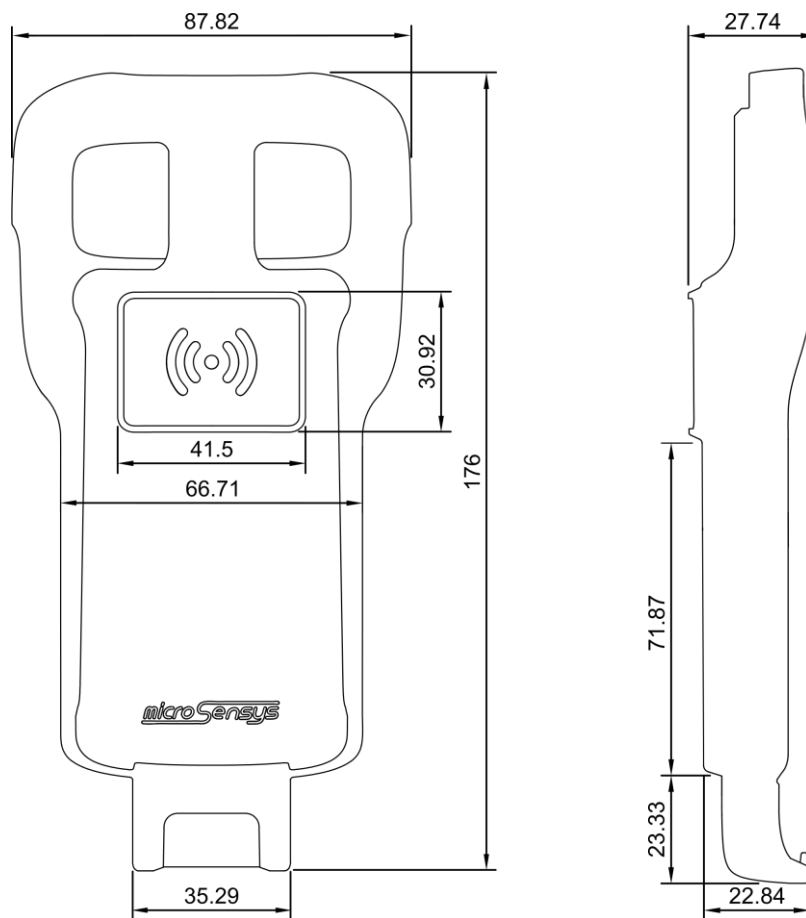
HOST Interface:

Mounting: ZEBRA TC78 expansion interface, back common I/O 8 pins
snap-on accessory
Power Supply: powered by ZEBRA TC78
Power Consumption: sleep: typ. 3 mA
idle: typ. 60 mA
HF active: typ. 160 mA
UHF active: max. 500 mA
Software Interface: iID® driver engine for Android™
Supported Commands: see API documentation of microsensys iID® driver engine

Mechanical / Environmental:

enclosed electronic module for mounting on handheld device
Dimensions:
Weight:
Material: LEXAN™ COPOLYMER EXL9330
Protection Class: IP 67
Working Temperature: -20 °C ... +60 °C
Storage Temperature: -25 °C ... +65 °C, recommended 25 °C

Dimensions:



all dimensions in mm